

Standard Features:

- Cost Effective Process
- User Friendly, Self Teach, Flexible Software
- Windows Based User Interface
- High Speed Defect Detection
- 100% Device Inspection
- Random or Fixed Sample Inspection with Programmable AQL
- Customized Inspection
- Ultra High Resolution Cameras and Optics
- Custom Programmable LED Lighting
- Yield, Defect, Machine, Product Type... Data Collection Center (DCC)
- Standard or Customer defined Reporting
- Expandable
- Pass Fail Mode – FASTEST UPH MODE
- Measure, Code Read, Correlate, Data Collect Mode*

*UPH Dependant on Wire Count, Measurements, Inspection Criteria etc...

Standard Inspection Capabilities:

- Missing Die
- Missing Wire / Misplaced Wire
- Wire Shorts
- Wire Breaks
- Ball Measurement
- Wire Measurement
- Wire Sag / Track
- Die Attach Wetting
- Epoxy Check. On Die or Lead
- Chipped or Crack Die
- Die Scratch
- Die Orientation
- Correct Die
- Theta Check
- Die Location
- Correct Wire Bond Location Verification
- Wire Bond Mapping
- Multi Die Verification / Missing Component on MCM's
- Ink Dot
- Foreign Particles
- Measurement
- Serial / Part Numbers / Bar Codes / Device Codes